

03/05/02 1132 U.S. PTO

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10/08/02 10/08/02 10/08/02

Assistant Commissioner for Patents  
Washington, DC 20231

DSMO File No. : M1071.1711  
Inventor : Hidekiyo TAKAOKA, et al.  
Title : LEAD FREE SOLDER AND SOLDERED ARTICLE  
Assignee : Murata Manufacturing Co., Ltd.

The present application is a divisional under 37 C.F.R. §1.53(b) of prior application Serial No. 09/632,819, filed August 7, 2000, by Hidekiyo TAKAOKA and Kiyotaka MAEGAWA, entitled LEAD FREE SOLDER AND SOLDERED ARTICLE.

Enclosed herewith please find the following documents in the above-identified application for United States Letters Patent:

- 21 Pages of Specification including Abstract and Claims
- 6 Numbered Claims Calculated as 6 Claims for Fee Purposes
- X Copy of Declaration and Power of Attorney from the prior application under 37 CFR § 1.63(d). The entire disclosure of the prior application is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated herein by reference.
- X Priority under 35 U.S.C. § 119 based on Japanese Application No. 10-16142, filed January 28, 1998, is claimed. The certified copy of the priority application has been filed in said prior application Serial No. 09/632,819, filed August 7, 2000.
- X The prior application was assigned to Murata Manufacturing Co., Ltd. and was recorded on August 31, 2000 at Reel 011073, Frame 0857.
- X Return Addressed Post Card

DSMO Check No. \_\_\_\_\_, which includes the fee of \$740.00, calculated as follows:

Basic Filing Fee: ..... \$ 740.00

Additional Filing Fees:

Total Number of Claims in Excess of 20, times \$18

Number of Independent Claims in Excess of 3, times \$84:

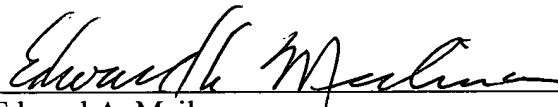
One or More Multiple Dependent Claims: Total \$280

Total Filing Fees ..... \$ 740.00

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed, or if any additional fee during the prosecution of this case is not paid, the Patent and Trademark Office is authorized to charge the underpayment to Deposit Account No. 041073.

Dated: March 6, 2002

Respectfully submitted,



Edward A. Meilman

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**LEAD-FREE SOLDER AND SOLDERED ARTICLE**

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09/632,819, filed August 7, 2000, in the name of Hidekiyo TAKAOKA and  
Kiyotaka MAEGAWA and entitled LEAD FREE SOLDER AND  
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23365 v1; \$1101!.DOC